PRODUCT DATA SHEET

NC-26S

Flip-Chip Flux

Introduction

NC-26S Flip-Chip Flux is a halogen-free, no-clean flip-chip dipping flux, which is designed to leave a completely benign, clear residue. The reduction in residue optimizes underfill adhesion and decreases possible outgassing during underfill cure.

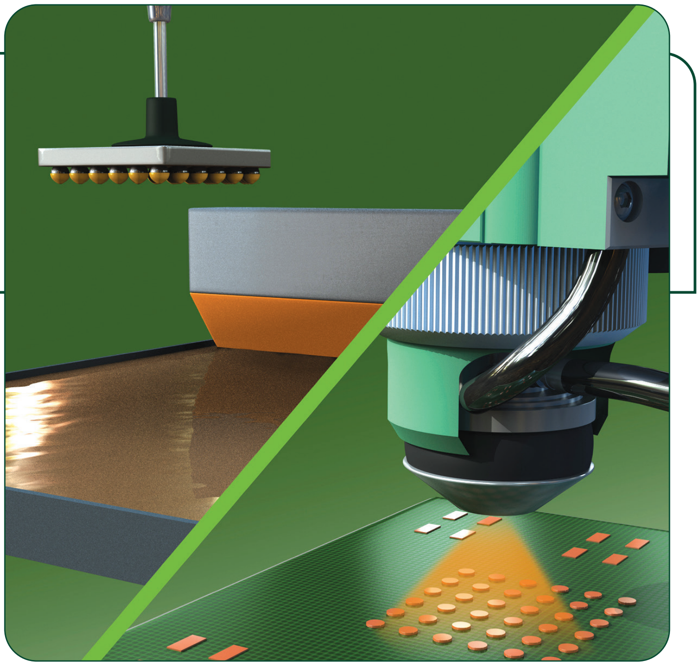
Features

- Designed for copper-pillar flip-chip dipping applications
- Tackiness suitable for holding multicore die during assembly
- Compatible with underfills
- No wetting onto die surface
- Dipping with minimal bridging
- Bubble-free airless packaging
- Low residue
- Halogen-free
- No-clean

Properties

	Value	Test Method
Flux Type	ORL0	J-STD-004 (IPC-TM-650: 2.3.32 and 2.3.33)
Color	Light Yellow	Visual
Typical Viscosity	13kcps	Brookfield CV-I. 51CPE Spindle @ 20rpm after 5 minutes
Typical Acid Value	39mg KOH/g	Titration
SIR (Ohms)	Pass	J-STD-004 (IPC-TM-650: 2.6.3.3 IPC-B-24)
Typical Post-Reflow Residual Weight	<10%	TGA Data
Working Life	≥8 hours	Customer Experience (Dipping)
Shelf Life	1 year when stored at 0–30°C	Viscosity Change/ Microscope Examination

All information is for reference only. Not to be used as incoming product specifications.



Application

NC-26S Flip-Chip Flux will have strong adhesion to epoxy-based underfill materials, especially epoxy-amine and epoxy-acid based chemistries. **NC-26S Flip-Chip Flux** should also be suitable for use with many epoxy-anhydride systems.

Cleaning

NC-26S Flip-Chip Flux is designed for no-clean applications. If necessary, the flux can be removed by using a commercially available flux cleaner. Please contact an Indium Corporation Technical Service Engineer for recommendations of cleaners to suit your process needs.

Packaging

NC-26S Flip-Chip Flux is most commonly available in 10–30g syringes. Other packaging can be provided to meet specific requirements.

Storage

NC-26S Flip-Chip Flux syringes and cartridges should be stored tip down for maximum shelf life. **NC-26S Flip-Chip Flux** should be allowed to reach ambient temperature before use if stored cold.

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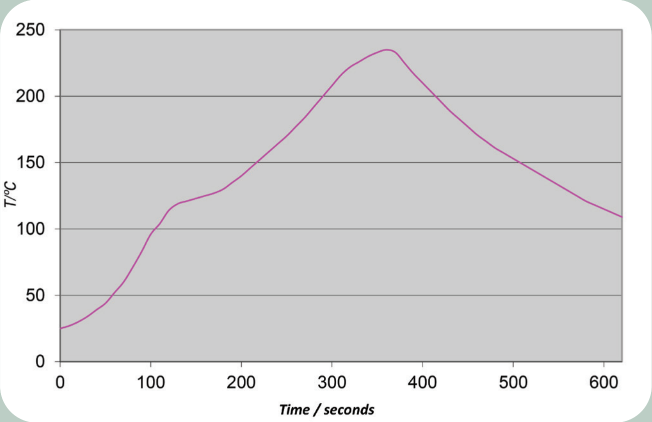
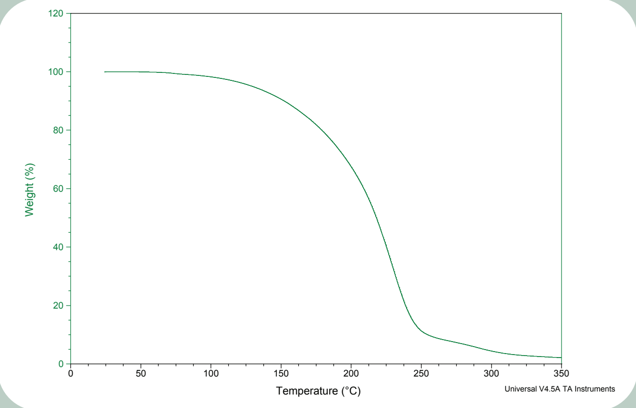
Reflow

Recommended Profile:



NC-26S Flip-Chip Flux is intended to be used in a nitrogen reflow environment of 100ppm oxygen or less. Some applications can utilize this material in an air environment, although best results will be obtained in an inert atmosphere. **NC-26S Flip-Chip Flux** can be used on many surface finishes including immersion Ag, Cu, and AuNi. These surfaces can be soldered with Pb-free alloys, but require nitrogen if reflow temperatures exceed 240°C.

Thermogravimetric Analysis (TGA)



TGA was performed at a ramp rate of 10°C per minute.

Technical Support

Indium Corporation sets the industry standard in providing rapid response, on-site technical support for our customers worldwide. Indium Corporation's team of Technical Support Engineers can provide expertise in all aspects of Materials Science and Semiconductor Packaging process applications.

Safety Data Sheets

Please refer to the SDS document within the product shipment, or contact our local team to receive a copy.

All of Indium Corporation's solder paste and preform manufacturing facilities are IATF 16949:2016 certified.
Indium Corporation is an ISO 9001:2015 registered company.